

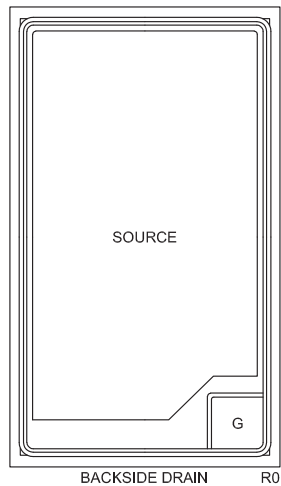
The CP372 medium power N-Channel MOSFET is optimized for power management and drive circuit applications where energy efficiency is a critical design element. The 7.5 mil thick die provides an ultra low profile device that is readily attached via wire bond techniques. Parametrically, low on-resistance and gate charge characteristics maximize efficient operation.

FEATURES:

- Low on-resistance, $r_{DS(ON)}$
- Low gate charge, Q_{GS}
- High drain current density
- Low profile geometry
- Metalization suitable for standard die attach technologies
- Top metalization optimized for wire bonding

APPLICATIONS:

- Power management
- Motor drives
- Load switching
- DC-DC conversion



MECHANICAL SPECIFICATIONS:

Die Size	37 x 63 MILS
Die Thickness	7.5 MILS
Gate Bonding Pad Area	6.9 x 6.8 MILS
Source Bonding Pad Area	30 x 55 MILS
Top Side Metalization	Al – 40,000Å
Back Side Metalization	Ti/Ni/Ag – 1,000Å/3,000Å/10,000Å
Scribe Alley Width	3.15 MILS
Wafer Diameter	8 INCHES
Gross Die Per Wafer	19,400

MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

	SYMBOL		UNITS
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	20	V
Continuous Drain Current (Steady State)	I_D	5.3	A
Maximum Pulsed Drain Current, $t_p=10\mu\text{s}$	I_{DM}	30	A
Operating and Storage Junction Temperature	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I_{GSSF}, I_{GSSR}	$V_{GS}=20\text{V}, V_{DS}=0$			100	nA
I_{DSS}	$V_{DS}=60\text{V}, V_{GS}=0$			1.0	μA
BV_{DSS}	$V_{GS}=0, I_D=250\mu\text{A}$	60			V
$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	1.0	1.3	3.0	V

CP372

N-Channel MOSFET Die

Enhancement-Mode

ELECTRICAL CHARACTERISTICS - Continued: ($T_A=25^\circ\text{C}$ unless otherwise noted)

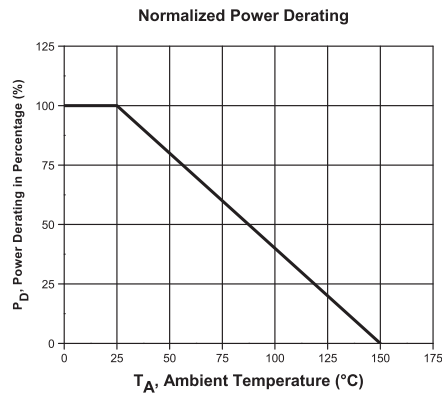
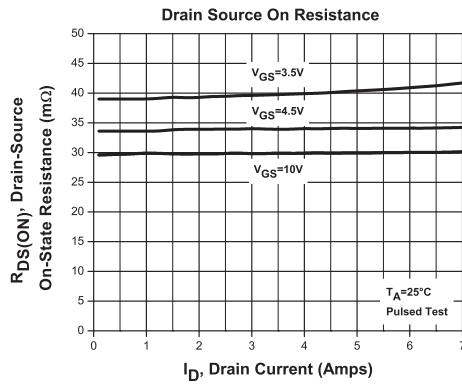
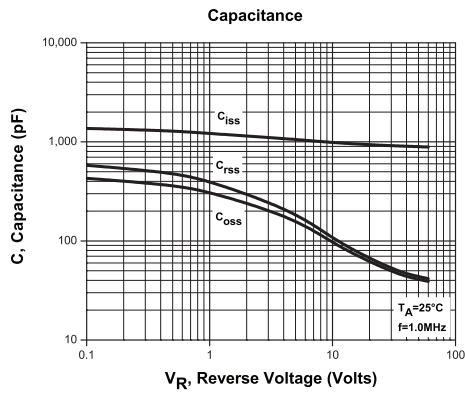
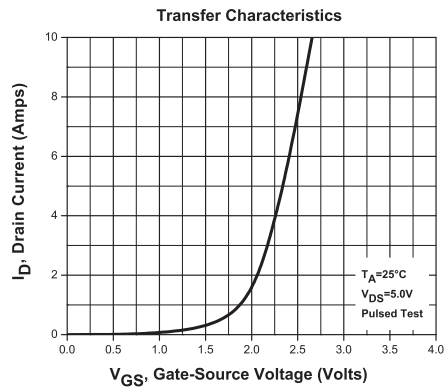
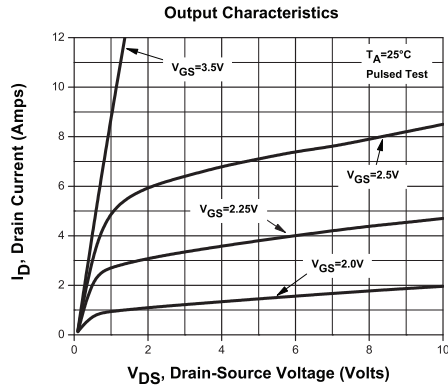
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
V_{SD}	$V_{GS}=0, I_S=2.0A$			1.2	V
$r_{DS(ON)}$	$V_{GS}=10V, I_D=5.3A$		30	41	m Ω
$r_{DS(ON)}$	$V_{GS}=4.5V, I_D=4.7A$		33	52	m Ω
$Q_{g(tot)}$	$V_{DS}=30V, V_{GS}=5.0V, I_D=5.3A$		8.8		nC
Q_{gs}	$V_{DS}=30V, V_{GS}=5.0V, I_D=5.3A$		1.9		nC
Q_{gd}	$V_{DS}=30V, V_{GS}=5.0V, I_D=5.3A$		3.6		nC
C_{rss}	$V_{DS}=30V, V_{GS}=0, f=1.0MHz$		53		pF
C_{iss}	$V_{DS}=30V, V_{GS}=0, f=1.0MHz$		920		pF
C_{oss}	$V_{DS}=30V, V_{GS}=0, f=1.0MHz$		49		pF
t_{on}	$V_{DD}=30V, V_{GS}=4.5V, I_D=4.4A$ $R_G=1.0\Omega, R_L=6.8\Omega$		33		ns
t_{off}	$V_{DD}=30V, V_{GS}=4.5V, I_D=4.4A$ $R_G=1.0\Omega, R_L=6.8\Omega$		42		ns

PACKING OPTIONS:

- CP372-WN: Full Wafer
- CP372-WR: Sawn Wafer on Plastic Ring
- CP372-CT: Singulated Die in Waffle Pack

CP372

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

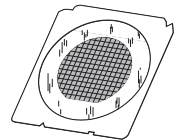
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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www.centrasemi.com/wwreps

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Product End of Life Notification

PDN ID:	PDN01170
Notification Date:	4/15/21
Last Buy Date:	Stock Only
Last Shipment Date	Stock Only

Please be advised that Central Semiconductor must immediately discontinue the product(s) listed in the attached PDN notice. Orders can only be accepted for products with available inventory on hand.

You may have purchased one or more of the products listed. Please do not hesitate to contact your local Central Semiconductor sales representative with any questions or needs you may have. Central regrets any inconvenience this may cause.

Sincerely,

Central Semiconductor Corp.

DISCLAIMER: This End of Life (EOL) notification is in accordance with JEDEC standard JESD48 - Product Discontinuance. Central Semiconductor Corp. will make every effort to offer life-time buy (LTB) opportunities and/or offer replacement devices to existing customers for discontinued devices, however, one or both may not be possible for all devices. Please contact your local Central Semiconductor sales representative for LTB opportunities/additional information.



<http://www.centrasemi.com>

Product End of Life Notification

PDN ID:	PDN01170
Notification Date:	4/15/21
Last Buy Date:	Stock Only
Last Shipment Date	Stock Only

Summary: The CP372 wafer process is being discontinued and is now classified as End of Life (EOL). Suggested replacement wafer process CP403 was previously announced in PCN187, July 23, 2020.

Although Central Semiconductor Corp. makes every effort to continue to produce devices that have been proclaimed EOL (End of Life) by other manufacturers, it is an accepted industry practice to discontinue certain devices when customer demand falls below a minimum level of sustainability. Accordingly, the following product(s) have been transitioned to End of Life status as part of Central's ongoing Product Management Process. Any replacement products are noted below. The effective date for placing last purchase orders will be six (6) months from the date of this notice and twelve (12) months from the notice date for final shipments, and minimum order quantities may apply. The last purchase and shipment dates may be extended if inventory is available.

*** All Plating types (PBFREE, TIN/LEAD) for each item listed are included in this notice.**

<u>Central Part Number</u>	<u>Suggested Replacement</u>
CP372-CT	CP403-CZDM0605N-CT
CP372-WN	CP403-WN

Central would be happy to assist you by providing additional information or technical data to help locate an alternate source if we have no replacement available. Please email your requests to engineering@centrasemi.com.

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